



PART NO. : TG111-E212NWRL

50PIN 0.040" LEAD PITCH SMT PACKAGE

DESIGNED FOR DUAL-PORT GIGABIT, IEEE802.3ab OR FOUR-PORT FAST ETHERNET, IEEE802.3u APPLICATIONS

COMPLIANT WITH IEEE802.3af REQUIREMENTS WITH 350mA CURRENT CARRYING CAPACITY FOR PoE

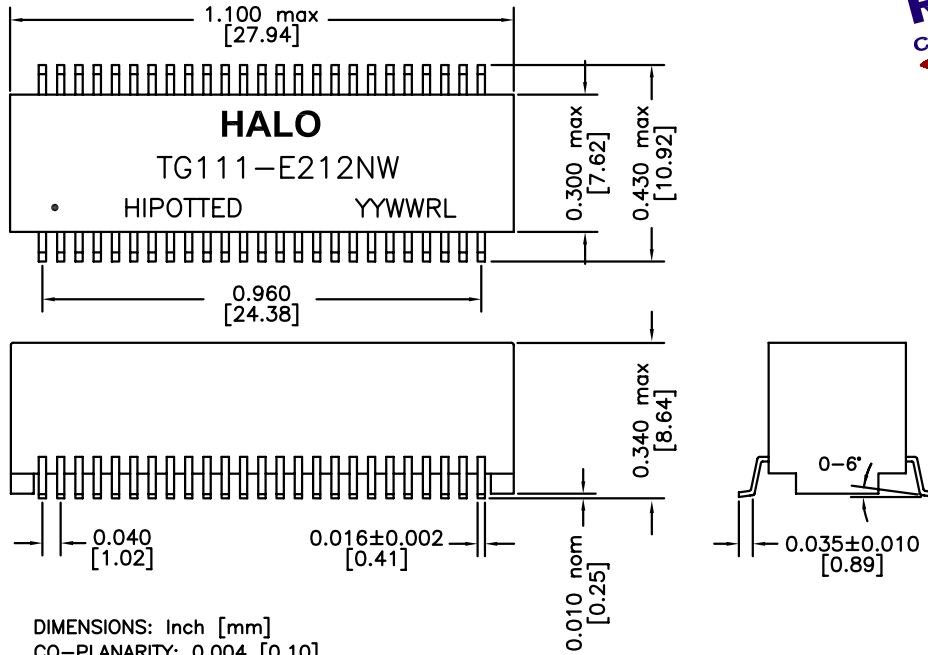
RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS CONDITION PER IPC/JEDEC J-STD-020C

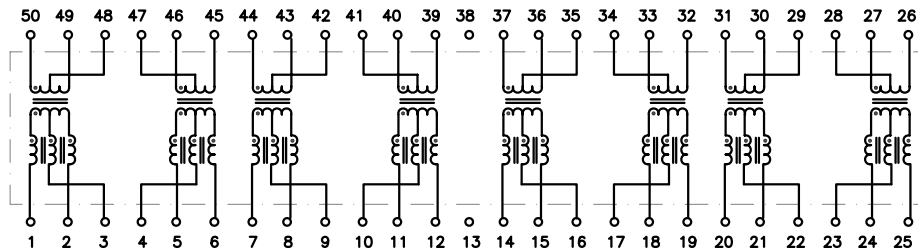
EXTENDED OPERATING TEMPERATURE -40/+85°C

ELECTRICAL SPECIFICATIONS @ 25° C

URNS RATIO	1CT:1CT±2%
OCL (100KHz,0.1Vrms,8mADC)	350µH min
INSERTION LOSS 1-100MHz	-1.1dB max
RETURN LOSS 1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CMR 1-100MHz	-40dB typ
CROSSTALK 1-30MHz	-50dB typ
60MHz	-45dB typ
100MHz	-40dB typ
ISOLATION	1,500Vrms



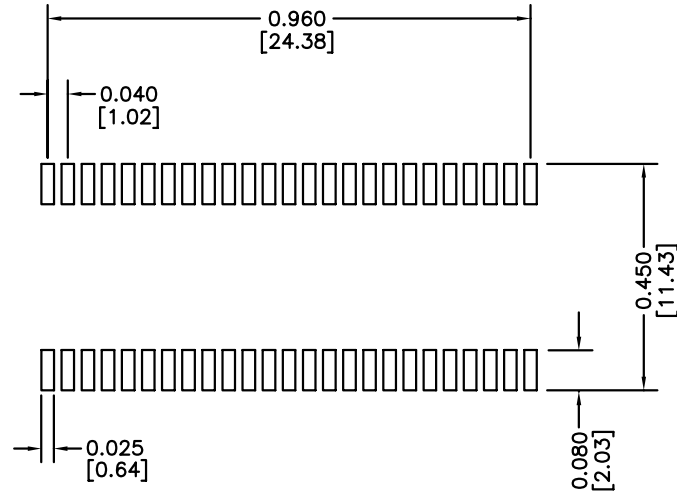
DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
	FOR	FAST/GIGABIT ETHERNET	DRAWN PETER LU	5/12/06	A	FIRST ISSUE	5/12/06
	PART NO.	TG111-E212NWRL	CHECKED LEI KEONG	3/20/08	B	PROD. RELEASE	8/31/06
	SCALE	NONE	APPROVED PETER LU	3/20/08	C	REV TOE LENGTH TOL.	3/20/08
	PAGE	1 OF 2	FILE	E212NWRL.DWG			



RECOMMENDED SOLDER PAD DIMENSIONS
 DIMENSIONS: Inch [mm]

HALO/PBL

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FOR	FAST/GIGABIT ETHERNET		DRAWN PETER LU	5/12/06	A	FIRST ISSUE	5/12/06
PART NO.	TG111-E212NWRL		CHECKED LEI KEONG	3/20/08	B	PROD. RELEASE	8/31/06
SCALE	NONE	PAGE 2 OF 2	APPROVED PETER LU	3/20/08	C	REV TOE LENGTH TOL.	3/20/08
FILE	E212NWRL.DWG						